

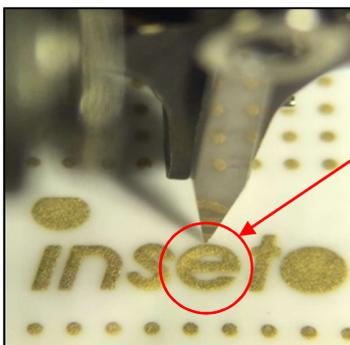
- SCOPE: Adjusting the correct working height for a Micro Point Pro (MPP) or Kulicke and Soffa (K&S) manual wire bonder workholder.

Setting Workholder Height

1. Apply power to the bonder and wait for the machine to initialise.
2. Set the LOOP value to 1.
3. Remove the work-holder from the bonding area.
4. Press and release the chessman button (bonding button) to bond in free air; this will move the bond-head downwards to the loop position.
5. Hold the work-holder static in the middle (below) and by rotating the base the height can be adjusted.
 - a. Rotate clockwise to raise workholder height.
 - b. Rotate anti-clockwise to lower workholder height.



6. Rotate workholder anticlockwise fully to lowest position.
7. Load workholder (with product to bond).
8. Position workholder under the bonding tool.
9. Looking through the microscope raise work holder until lowest bonding surface is just touching the tool.

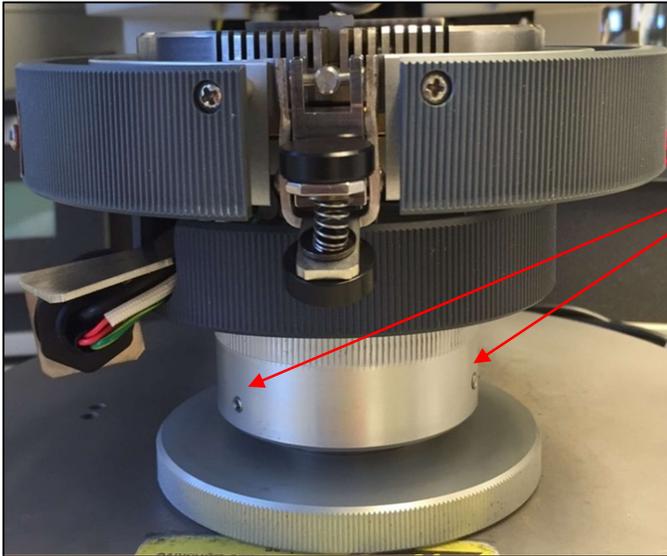


The image above shows the tool touching down onto the ceramic

10. Press the RESET button, the machine will now initialise.
11. Increase the LOOP parameter to a higher value (4 - 5) to ensure good clearance above product.
12. The work holder height is now setup correctly.

Troubleshooting:

- **Problem:** - The work-holder will not move in any direction (upwards or downwards).
- **Resolution:** - The spring grub screws are too tight, loosen all 3 grub screws slightly until rotation is possible.



2 grub screws are visible in this figure (another is located at the back of the workholder)

Loosen grub screws to facilitate rotation.

For further information on Micro Point Pro equipment :

<https://www.inseto.co.uk/microelectronic-equipment-mpp-manual-wire-bonders.php>

<https://www.inseto.co.uk/microelectronic-materials-mpp-bonding-tools.php>